

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Wood et al.

**Serial No.:** 10/666,742

**Filed:** September 19, 2003

**For:** METHODS FOR THINNING  
SEMICONDUCTOR SUBSTRATES THAT  
EMPLOY SUPPORT STRUCTURES  
FORMED ON THE SUBSTRATES  
(Amended)

**Confirmation No.:** 6057

**Examiner:** A. Ghyka

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-6095US  
(2003-0593.00/US)

**Notice of Allowance Dated:**

December 17, 2009

**VIA ELECTRONIC FILING  
March 15, 2010**

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 3 of this paper;

**A listing of the claims** begins on page 5 of this paper; and

**Remarks** start at page 8 of this paper.